

SEMICONDUCTOR





TO220 package

KM series



High power dissipation, extruded heatsinks designed to accommodate one or more TO220 packages via a clip retaining feature (clips available separately). Shaped to minimise board space, with a threaded slot provided to aid assembly. Choice of thermal resistance.

		Manf. Part No. &
Th. Res.	Length (L)	Order Code
3.7°C/W	75mm	KM75-1
Device retaining clip (with legs) Device retaining clip (without legs for		4426 4525
space saving)		